

CELANYL® B3 W GB30 NC 1102

CELANYL®

This compound is designed for easy injection molding processing. It is suitable for Automotive, Electrical and Electronic and Industrial & Consumer applications.

Product information

Resin Identification	PA6-GB30	ISO 1043
Part Marking Code	>PA6-GB30<	ISO 11469

Rheological properties

	dry/cond.		
Viscosity number	145/*	cm ³ /g	ISO 307, 1628
Moulding shrinkage range, parallel	0.9 - 1.2	%	ISO 294-4, 2577
Moulding shrinkage range, normal	0.9 - 1.2	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile modulus	4300/-	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	70/-	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	5/-	%	ISO 527-1/-2
Charpy impact strength, 23°C	30/-	kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	3/-	kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C	3.2/-	kJ/m ²	ISO 180/1A
Ball indentation hardness, H 961/30	170/-	MPa	ISO 2039-1
Poisson's ratio	0.36/- ^[C]		

[C]: Calculated

Thermal properties

	dry/cond.		
Melting temperature, 10°C/min	225/*	°C	ISO 11357-1/-3

Flammability

	dry/cond.		
Burning Behav. at 1.5mm nom. thickn.	HB/*	class	IEC 60695-11-10
UL recognition	yes/*		UL 94

Electrical properties

	dry/cond.		
Volume resistivity	1E13/-	Ohm.m	IEC 62631-3-1
Comparative tracking index	550/-		IEC 60112

Physical/Other properties

	dry/cond.		
Humidity absorption, 2mm	1.8/*	%	Sim. to ISO 62
Water absorption, 2mm	6.3/*	%	Sim. to ISO 62
Density	1330/-	kg/m ³	ISO 1183

Injection

Drying Recommended	yes
Drying Temperature	80 °C
Drying Time, Dehumidified Dryer	2 - 4 h
Processing Moisture Content	≤0.15 %
Melt Temperature Optimum	260 °C
Min. melt temperature	240 °C

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Max. melt temperature	290 °C
Screw tangential speed	≤0.2 m/s
Mold Temperature Optimum	80 °C
Min. mould temperature	60 °C
Max. mould temperature	120 °C

Characteristics

Processing	Injection Moulding
Delivery form	Granules
Special characteristics	Heat stabilised or stable to heat, High Flow, Low Warpage